# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**  
[List multiple models if applicable.]  
HP ENVY Notebook PC  
HP ENVY Notebook  
HP ENVY Notebook 17

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.  
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of Items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB,USB board,Power board,TouchPad</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Cell Baterry &amp; RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner
Include the cartridges, print heads, tubes, vent chambers, and service stations.

Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove battery module
2. Dis-fasten All Base screw*20
3. Disassemble Base cap
4. Dis-fasten Base cap screw*4
5. Remove ODD
6. Disassemble Base
7. Pull out FFC*3(Touchpad, Power, USB)
8. Pull out FFC*2(HDD, ODD)
9. Pull out KB membrane, backlit(backlit sku only)
10. Pull out HDD module
11. Dis-fasten daughter boards screw*2 (USB)
12. Remove daughter board (USB)
13. Pull out wire cable connectors*3 (LCD, DC cable, Battery cable)
14. Pull out wire cable*2 (speaker, Fan)
15. Pull out Antenna
16. Dis-fasten Hinge screw*4
17. Remove hinge up
18. Dis-fasten Power board screw*2
19. Remove daughter board(Power)
20. Remove Batter cable
21. Remove ODD cable
22. Dis-fasten motherboard screw*5
23. Dis-fasten Fan screw*2
24. Remove Fan
25. Remove motherboard
26. Dis-fasten Speaker R&L screw*1
27. Remove speaker L & R
28. Dis-fasten thermal module screw*6
29. Remove thermal module
30. Remove LCD Bezel screw pad
31. Dis-fasten LCD Bezel screws*2
32. Remove LCD bezel
33. Dis-fasten Hinge BKT screw*6
34. Dis-fasten LCD BKT L & R screws*4
35. Remove LCD module
36. Remove Camera module
37. Remove Antenna cables L & R

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly

3.22 Remove battery module
3.23 Remove bottom cover

3.24 LCD module set disassembly

3.25 Base case disassembly

PSG instructions for this template are available at EL-MF877-01
3.26 Thermal module and mother board disassembly

3.27 Top case disassembly